Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

- 1-5. (canceled)
- (withdrawn) Method for manufacturing a bulk acoustic wave resonator comprising the steps of

providing a holder in the form of a silicon chip or dice,

disposing a top electrode on the silicon dice,

disposing a piezoelectric layer,

disposing a bottom electrode,

disposing a Bragg reflector,

disposing a front side absorbing layer,

disposing a substrate, and

removing the holder.

- (new) A bulk acoustic wave (BAW) resonator comprising:
 - a top electrode:
 - a piezoelectric layer disposed adjacent to the top electrode;
- a bottom electrode disposed adjacent to the piezoelectric layer, wherein the bottom electrode is disposed opposite the top electrode relative to the piezoelectric layer; and
- a substrate disposed opposite the piezoelectric layer relative to the bottom electrode, wherein the substrate comprises an uneven surface to suppress a spurious mode.

- 8. (new) The BAW resonator of claim 7, wherein the uneven surface of the substrate comprises a roughened surface to scatter the spurious mode.
- (new) The BAW resonator of claim 8, wherein the roughened surface of the substrate comprises an etched surface of glass.
- (new) The BAW resonator of claim 8, wherein the roughened surface of the substrate comprises a blasted layer of glass.
- 11. (new) The BAW resonator of claim 7, wherein the uneven surface of the substrate comprises an absorbing layer disposed on the substrate to absorb the spurious mode.
- 12. (new) The BAW resonator of claim 11, wherein the absorbing layer is disposed on a front side of the substrate, between the substrate and the bottom electrode.
- 13. (new) The BAW resonator of claim 11, wherein the absorbing layer is disposed on a rear side of the substrate, opposite the bottom electrode relative to the substrate.
- 14. (new) The BAW resonator of claim 11, wherein the absorbing layer comprises at least one acoustic absorbing material of a plurality of acoustic absorbing materials, wherein the plurality of acoustic absorbing materials comprises epoxy glue, an elasticoviscous material, rubber, silicon rubber, a plastic material, a porous media, and a porous thin film.
- (new) The BAW resonator of claim 7, further comprising a Bragg reflector disposed between the substrate and the bottom electrode.
- (new) The BAW resonator of claim 7, wherein:
 the top electrode comprises a first metal material:

the piezoelectric layer comprises at least one of a plurality of piezoelectric material; and

the bottom electrode comprises a second metal material.

- (new) The BAW resonator of claim 16, wherein the first metal material of the top electrode comprises aluminum (Al).
- (new) The BAW resonator of claim 16, wherein the plurality of piezoelectric materials comprises aluminum nitride (AlN), zinc oxide (ZnO), and lead zirconate titanate (PZT)
- 19. (new) The BAW resonator of claim 16, wherein the second metal material of the bottom of electrode comprises molybdenum (Mo), platinum (Pt), or tungsten (W).
- 20. (new) A bulk acoustic wave (BAW) filter comprising:
 - a first BAW resonator to suppress a pass-band ripple of a spurious mode; and
- a second BAW resonator connected to the first BAW resonator, the second BAW resonator to suppress the pass-band ripple of a spurious mode:

wherein each of the first and second BAW resonators comprises a substrate with an uneven surface to suppress a spurious mode.

- 21. (new) The BAW filter of claim 20, wherein the first and second BAW resonators are connected in a ladder configuration.
- (new) The BAW filter of claim 20, wherein the first and second BAW resonators are connected in a lattice configuration.
- 23. (new) The BAW filter of claim 20, wherein each of the first and second BAW resonators comprises:
 - a top electrode;
 - a piezoelectric layer disposed adjacent to the top electrode; and
- a bottom electrode disposed adjacent to the piezoelectric layer, wherein the bottom electrode is disposed opposite the top electrode relative to the piezoelectric layer; wherein the substrate is disposed opposite the piezoelectric layer relative to the bottom electrode.

- 24. (new) The BAW filter of claim 20, wherein the uneven surface of the substrate comprises a roughened surface to scatter the spurious mode.
- 25. (new) The BAW filter of claim 20, wherein the uneven surface of the substrate comprises an absorbing layer disposed on the substrate to absorb the spurious mode.